506327443 10/29/2020

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
LUNG-KUN CHU	03/09/2020
MAO-LIN HUANG	03/09/2020
CHUNG-WEI HSU	03/09/2020
JIA-NI YU	03/09/2020
KUO-CHENG CHIANG	03/11/2020
CHIH-HAO WANG	03/18/2020

RECEIVING PARTY DATA

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City:	HSINCHU
State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16802275

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	MARIA TEDESCO
SIGNATURE:	/Maria Tedesco/
DATE SIGNED:	10/29/2020

506327443 PATENT REEL: 054206 FRAME: 0277

Total Attachments: 3

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> PATENT REEL: 054206 FRAME: 0278



Docket No.: P20190614US00/24061.4083US01 Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

(1)	Lung-Kun Chu	of	New Taipei City, Taiwan (R.O.C.)
(2)	Mao-Lin Huang	of	Hsinchu City, Taiwan (R.O.C.)
(3)	Chung-Wei Hsu	of	Hsinchu County, Taiwan (R.O.C.)
(4)	Jia-Ni Yu	of	New Taipei City, Taiwan (R.O.C.)
(5)	Kuo-Cheng Chiang	of	Hsinchu County, Taiwan (R.O.C.)
(6)	Chih-Hao Wang	of	Hsinchu County, Taiwan (R.O.C.)

have invented certain improvements in

TRANSISTORS WITH DIFFERENT THRESHOLD VOLTAGES

for which we have executed an application for Letters Patent of the United States of America,

X	of even date filed herewith; and
	filed on February 26, 2020 and assigned application number 16/802,275; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name:	Lung-Kun Chu	
Residence Address:	New Taipei City, Taiwan (R.O.	C.)
Dated: >0 >0 /	7/9	Lug-Km Chw Inventor Signature
Inventor Name:	Mao-Lin Huang	
Residence Address:	Hsinchu City, Taiwan (R. O. C.)
Dated: 70 70 /	3/9	Marolin Hrang Inventor Signature
Inventor Name:	Chung-Wei Hsu	
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Dated: 2020	3 / 9	<u>Chung - Wel Ster</u> Inventor Signature
Inventor Name:	Jia-Ni Yu	
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Dated: 2020 /	3/9	<u>Jia Hi</u> Inventor Signature

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Inventor Name:

Kuo-Cheng Chiang

Residence Address:

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ww/3/11

Inventor Signature

Inventor Name:

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Dated: 3/18/2020

Inventor Signature

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